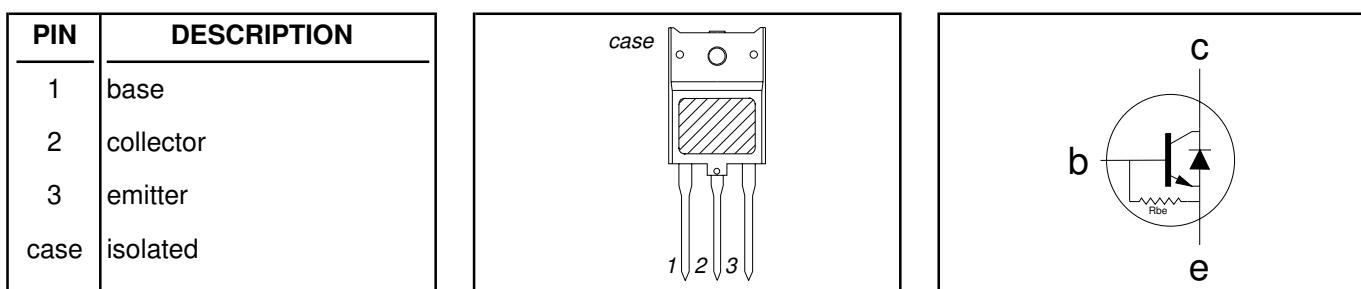


**Silicon Diffused Power Transistor****BU2527DX****GENERAL DESCRIPTION**

New generation, high-voltage, high-speed switching npn transistor with integrated damper diode in a plastic full-pack envelope intended for use in horizontal deflection circuits of high resolution monitors. Features improved RBSOA performance.

**QUICK REFERENCE DATA**

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
$V_{CESM}$	Collector-emitter voltage peak value	$V_{BE} = 0 \text{ V}$	-	1500	V
$V_{CEO}$	Collector-emitter voltage (open base)		-	800	V
$I_C$	Collector current (DC)		-	12	A
$I_{CM}$	Collector current peak value		-	30	A
$P_{tot}$	Total power dissipation	$T_{hs} \leq 25 \text{ }^\circ\text{C}$	-	45	W
$V_{CEsat}$	Collector-emitter saturation voltage	$I_C = 8.0 \text{ A}; I_B = 1.6 \text{ A}$	-	5.0	V
$I_{Csat}$	Collector saturation current	$f = 64 \text{ kHz}$	6.0	-	A
$t_s$	Storage time	$I_{Csat} = 6.0 \text{ A}; f = 64 \text{ kHz}$	1.7	2.0	$\mu\text{s}$

**PINNING - SOT399****PIN CONFIGURATION****SYMBOL****LIMITING VALUES**

Limiting values in accordance with the Absolute Maximum Rating System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CESM}$	Collector-emitter voltage peak value	$V_{BE} = 0 \text{ V}$	-	1500	V
$V_{CEO}$	Collector-emitter voltage (open base)		-	800	V
$I_C$	Collector current (DC)		-	12	A
$I_{CM}$	Collector current peak value		-	30	A
$I_B$	Base current (DC)		-	8	A
$I_{BM}$	Base current peak value		-	12	A
$-I_{B(AV)}$	Reverse base current	average over any 20 ms period	-	200	mA
$-I_{BM}$	Reverse base current peak value <sup>1</sup>		-	7	A
$P_{tot}$	Total power dissipation	$T_{hs} \leq 25 \text{ }^\circ\text{C}$	-	45	W
$T_{stg}$	Storage temperature		-65	150	$^\circ\text{C}$
$T_j$	Junction temperature		-	150	$^\circ\text{C}$

**THERMAL RESISTANCES**

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
$R_{thj-hs}$	Junction to heatsink	without heatsink compound	-	3.7	K/W
$R_{thj-hs}$	Junction to heatsink	with heatsink compound	-	2.8	K/W
$R_{thj-a}$	Junction to ambient	in free air	35	-	K/W

<sup>1</sup> Turn-off current.

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**ISOLATION LIMITING VALUE & CHARACTERISTIC** $T_{hs} = 25^\circ\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{isol}$	Repetitive peak voltage from all three terminals to external heatsink	R.H. $\leq 65\%$ ; clean and dustfree	-		2500	V
$C_{isol}$	Capacitance from T2 to external heatsink	$f = 1\text{ MHz}$	-	22	-	pF

**STATIC CHARACTERISTICS** $T_{hs} = 25^\circ\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_{CES}$	Collector cut-off current <sup>2</sup>	$V_{BE} = 0\text{ V}; V_{CE} = V_{CESMmax}$	-	-	1.0	mA
$V_{CES}$		$V_{BE} = 0\text{ V}; V_{CE} = V_{CESMmax}$	-	-	2.0	mA
$V_{CEO}sust$	Collector-emitter sustaining voltage	$T_j = 125^\circ\text{C}$	800	-	-	V
$I_{EBO}$	Emitter cut-off current	$I_B = 0\text{ A}; I_C = 100\text{ mA}$	-	110	-	mA
$R_{EB}$	Base-emitter resistance	$V_{EB} = 6.0\text{ V}$	-	55	-	$\Omega$
$BV_{EBO}$	Emitter-base breakdown voltage	$I_B = 600\text{ mA}$	7.5	13.5	-	V
$V_{CEsat}$	Collector-emitter saturation voltage	$I_C = 8.0\text{ A}; I_B = 1.6\text{ A}$	-	-	5.0	V
$V_{BESat}$	Base-emitter saturation voltage	$I_C = 8.0\text{ A}; I_B = 1.6\text{ A}$	-	-	1.1	V
$h_{FE}$	DC current gain	$I_C = 1\text{ A}; V_{CE} = 5\text{ V}$	-	11	-	
$h_{FE}$		$I_C = 8\text{ A}; V_{CE} = 5\text{ V}$	5	7	10	
$V_F$	Diode forward voltage	$I_F = 8\text{ A}$	-	1.6	2.0	V

**DYNAMIC CHARACTERISTICS** $T_{hs} = 25^\circ\text{C}$  unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
$C_c$	Collector capacitance	$I_E = 0\text{ A}; V_{CB} = 10\text{ V}; f = 1\text{ MHz}$	145	-	pF
$t_s$	Switching times (64 kHz line deflection circuit)	$I_{Csat} = 6.0\text{ A}; L_C = 170\text{ }\mu\text{H}$ $C_{fb} = 5.4\text{ nF}; I_{B(end)} = 0.55\text{ A}$ $L_B = 0.6\text{ }\mu\text{H}; -V_{BB} = 4\text{ V}; I_{BM} = 3.6\text{ A}$	1.7 0.1	2.0 0.2	$\mu\text{s}$ $\mu\text{s}$
$t_f$	Turn-off storage time Turn-off fall time				
$V_{fr}$	Anti-parallel diode forward recovery voltage	$I_F = 8\text{ A}; dI_F/dt = 50\text{ A}/\mu\text{s}$	16	-	V
$t_{fr}$	Anti-parallel diode forward recovery time	$V_F = 5\text{ V}$	410	-	ns

<sup>2</sup> Measured with half sine-wave voltage (curve tracer).

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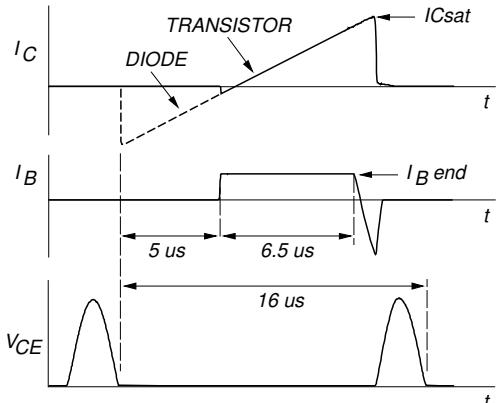


Fig.1. Switching times waveforms.

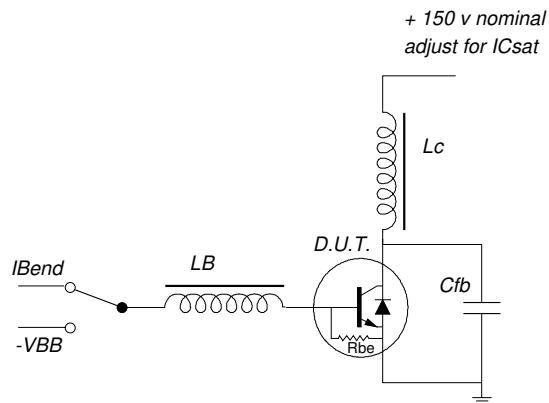


Fig.4. Switching times test circuit.

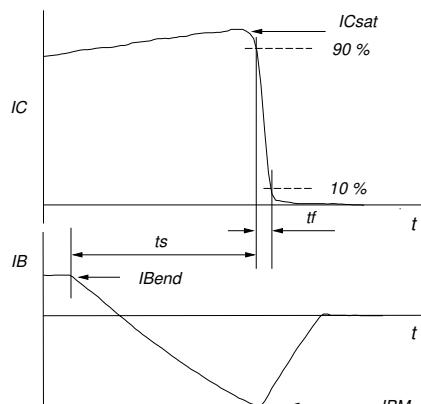
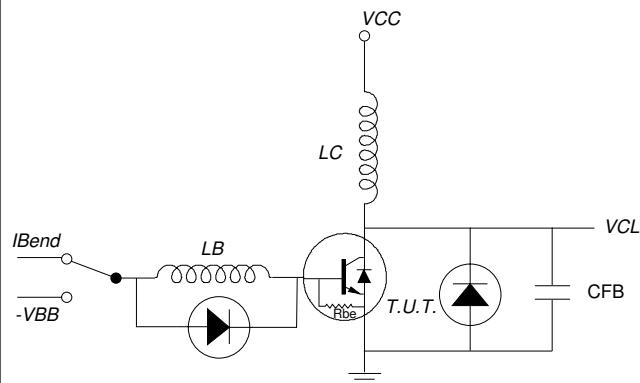
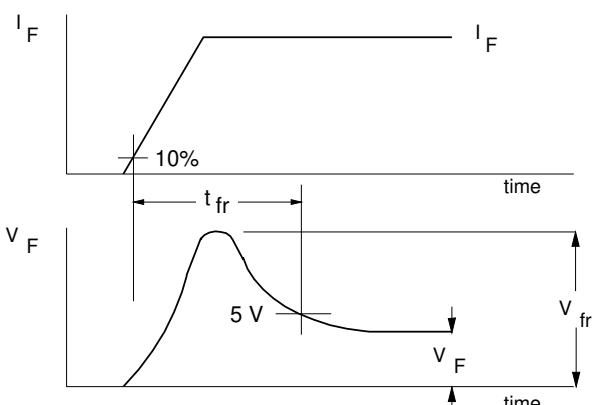
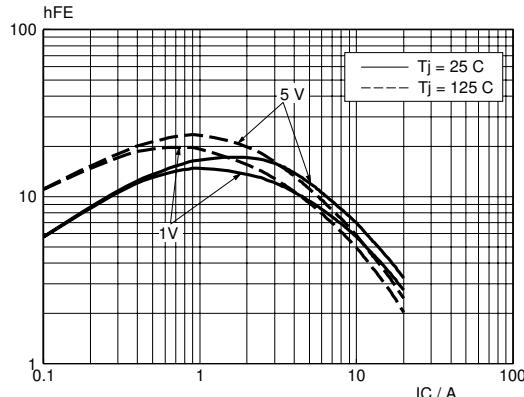


Fig.2. Switching times definitions.

Fig.5. Test Circuit RBSOA.  $V_{CC} = 140$  V;  $-V_{BB} = 4$  V;  
 $L_C = 100 - 200 \mu H$ ;  $V_{CL} \leq 1500$  V;  $L_B = 3 \mu H$ ;  
 $C_{FB} = 1 - 2.2$  nF;  $I_B(\text{end}) = 1 - 2$  AFig.3. Definition of anti-parallel diode  $V_{fr}$  and  $t_{fr}$ Fig.6. Typical DC current gain.  $h_{FE} = f(I_C)$   
parameter  $V_{CE}$

## Silicon Diffused Power Transistor

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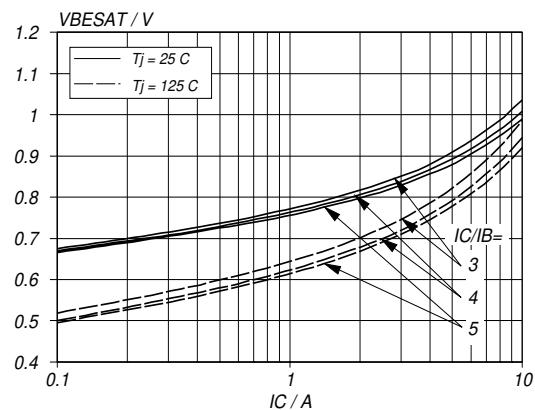


Fig.7. Typical base-emitter saturation voltage.  
 $V_{BEsat} = f(I_C)$ ; parameter  $I_C/I_B$

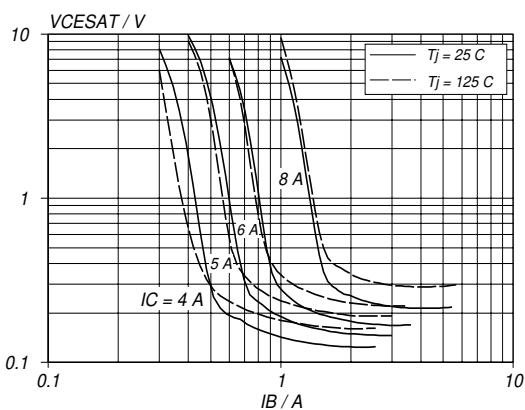


Fig.10. Typical collector-emitter saturation voltage.  
 $V_{CESat} = f(I_B)$ ; parameter  $I_C$

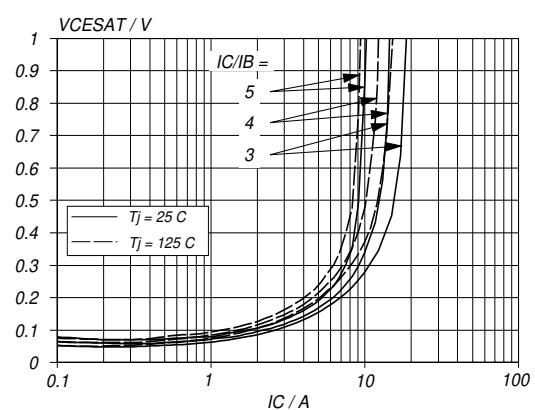


Fig.8. Typical collector-emitter saturation voltage.  
 $V_{CESat} = f(I_C)$ ; parameter  $I_C/I_B$

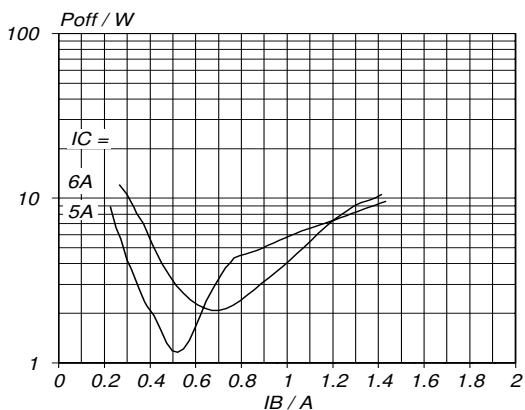


Fig.11. Typical turn-off losses.  $T_j = 85^\circ C$   
 $E_{off} = f(I_B)$ ; parameter  $I_C$ ;  $f = 64$  kHz

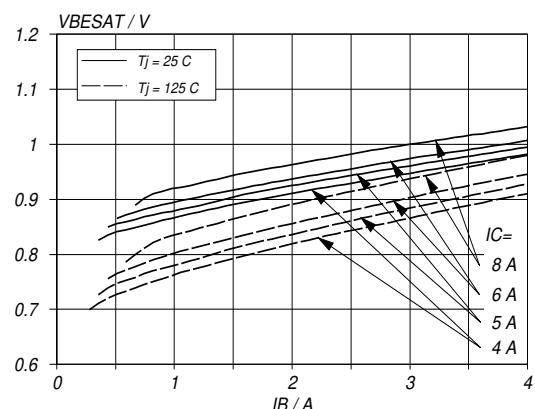


Fig.9. Typical base-emitter saturation voltage.  
 $V_{BEsat} = f(I_B)$ ; parameter  $I_C$

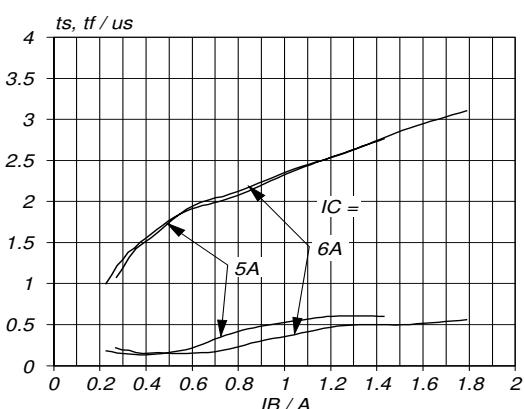


Fig.12. Typical collector storage and fall time.  
 $t_s = f(I_B)$ ;  $t_f = f(I_B)$ ; parameter  $I_C$ ;  $T_j = 85^\circ C$ ;  $f = 64$  kHz

## Silicon Diffused Power Transistor

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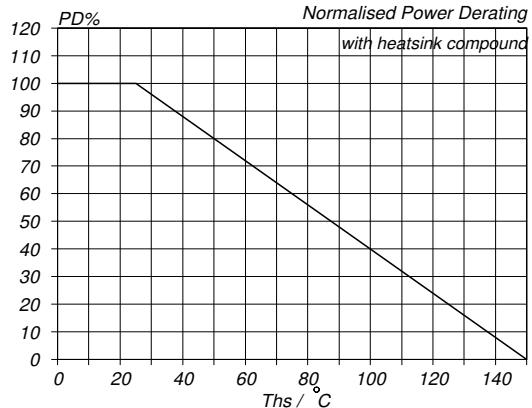


Fig.13. Normalised power dissipation.  
 $PD\% = 100 \cdot P_D / P_{D,25^\circ C} = f(T_{hs})$

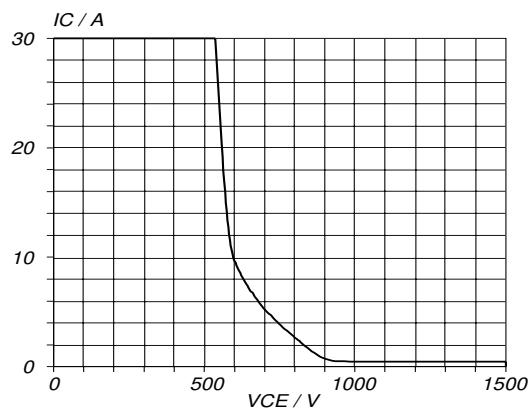


Fig.15. Reverse bias safe operating area.  $T_j \leq T_{j,max}$

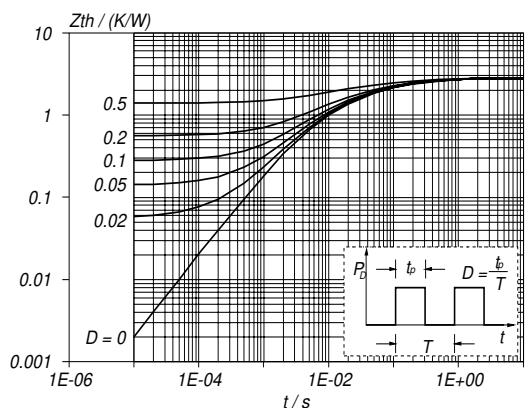


Fig.14. Transient thermal impedance.  
 $Z_{th,j-hs} = f(t); \text{parameter } D = t_p/T$

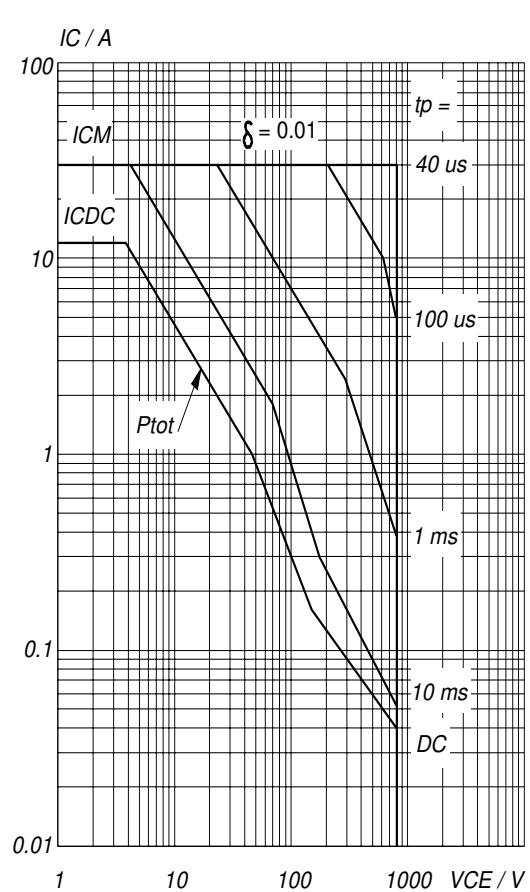


Fig.16. Forward bias safe operating area.  $T_{hs} = 25^\circ C$   
 $I_{CDC} \& I_{CM} = f(V_{CE}); I_{CM}$  single pulse; parameter  $t_p$ .  
Second-breakdown limits independant of temperature.  
Mounted with heatsink compound.

## Silicon Diffused Power Transistor

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**MECHANICAL DATA***Dimensions in mm*

Net Mass: 5.88 g

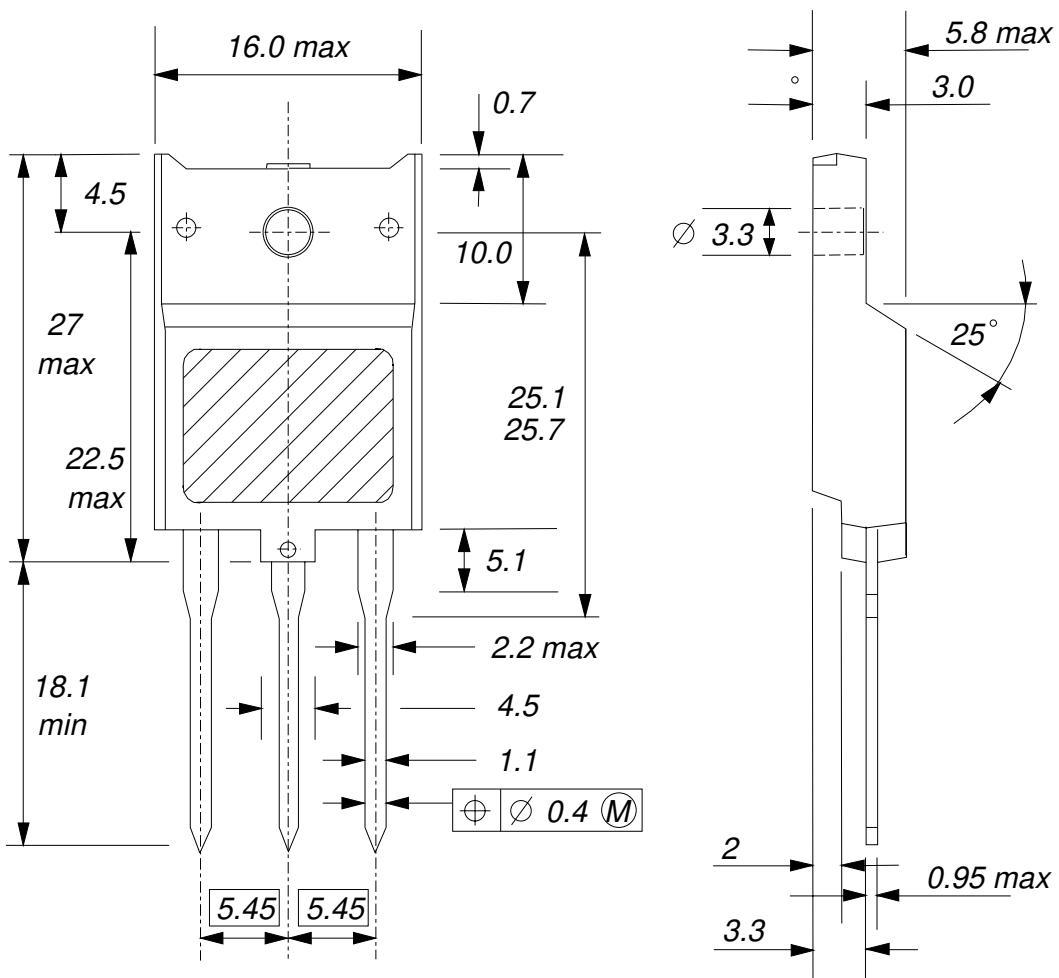


Fig.17. SOT399; The seating plane is electrically isolated from all terminals.

**Notes**

1. Refer to mounting instructions for F-pack envelopes.
2. Epoxy meets UL94 V0 at 1/8".

**Silicon Diffused Power Transistor****BU2527DX****DEFINITIONS**

<b>Data sheet status</b>	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
<b>Limiting values</b>	
Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
<b>Application information</b>	
Where application information is given, it is advisory and does not form part of the specification.	
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